

Program

Day 1 Tuesday - 30th January 2018

08.30 – 09.00

Registration and coffee

Session 1

09.00 – 09.45

Introduction to the seminar
Humidity effects in electronics
and reliability issues

Rajan Ambat
Center for Electronic
Corrosion, Technical
University of Denmark

09.45 – 10.20

Environment-induced corrosion of
wire bonds in Microelectronics

Orla O'Halloran
NXP semiconductors,
Netherlands

10.20 – 10.55

Interaction of Liquids with
Electronic Systems: Thermal
Events

Schultz Katharina
Automotive Electronics,
Robert Bosch, Germany

10.55 – 11.20

Coffee break

Session 2

11.20 - 11.55

Corrosion phenomena in
automotive electronics

Oliver Senftleben
Audi, Germany

11.55 – 12.30

An overview of electrochemical
corrosion on lead-free solder
alloys

Bálint Medgyes
BME Budapest

12.30 – 13.30

Lunch Break

Session 3

13.30 – 14.05	Electrochemical failure mechanisms at the semiconductor-packaging interface	Sophie Mach Automotive Electronics, Robert Bosch, Germany
14.05 – 14.40	Solderability and Reliability Evolution of No-Clean Solder Fluxes For Selective Soldering	Emmanuelle Guéné, Inventec, France
14.40 – 15.15	Outgassing in Polymers – Analysis and Consequences for Functional Foils	Allan Hjarbæk Holm Grundfos, Denmark
15.15 – 15.40	Coffee break	

Session 4

15.40 – 16.15	Reliability Assessment of No-clean and Water-soluble Solder Pastes	Mélanie Mathon Inventec, France
16.15 – 16.50	Short time Corrosion tests for electronic materials using thin layer coupons	Lutz Muller Center for Electronic Corrosion, Robert Bosch, Germany
16.50 – 17.00	Concluding remarks for first day	Rajan Ambat Center for Electronic Corrosion, Technical University of Denmark
17.00 – 19.30	Match making event organized by B2 Match and working dinner	

Day 2 | Wednesday – 31st January 2018

08.45 – 09.00

Arrival and coffee

Session 1

09.00 – 09.35

Reliability aspects - from global to local load

Seifritz Steffen
Automotive Electronics,
Robert Bosch, Germany

09.35 – 10.10

Indoor aerosol and gas chemistry:
a challenge/risk for electronic
reliability

Luca Ferrero
University of Milan-Bicocca,
Italy

10.10 – 10.45

Humidity build up in electronic
enclosures and defining design
parameters

Helene Conseil
Center for Electronic
Corrosion, Technical
University of Denmark

10.45 – 11.10

Coffee break

Session 2

11.10 – 11.45

Overview of fluid flow and RC
modelling of humidity build in
electronic systems

Sankhya Mohanty
Process Modelling Group,
Technical University of
Denmark

11.45 – 12.20

Humidity testing at Device level and
analysis of failure modes

Kim Schmidt
Force Technology,
Denmark
Morten Jellesen
Center for Electronic
Corrosion, Technical
University of Denmark

12.20 – 13.20

Lunch Break

Session 3

13.20 – 14.55	Selection of Protective Measures for Humidity Robust Electronics	Helmut Schweigart Zestron, Germany
14.55 – 15.30	Surface Insulation Resistance testing of conformal coatings used in electronics	Laura Frisk Trelic, Finland
15.30 – 16.05	TBA	
16.05 – 16.15	Conclusion and end of seminar	Rajan Ambat Center for Electronic Corrosion, Technical University of Denmark